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First Named Inventor: Kuri-Shi Lee
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Disclosure Statement

Application Number: 09/687,048
Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-Shi Tae Leon Lee

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Comments:

Electronic Information Disclosure Statement



LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application:



09/687048

Confirmation: 1120

Applicant(s): Kuri-Shi Lee

Docket

Number:

AMKOR-052A

Group Art

Unit:

2814

Examiner:

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US Patent Documents